



**Faculty of Manufacturing Engineering**

**IMPROVEMENT OF CHANGE GLUE SCHEDULE DOWN TIME AT  
LID ATTACHMENT PROCESS FOR SEMICONDUCTOR DEVICES**

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**Master of Manufacturing Engineering**

**2017**

**IMPROVEMENT OF CHANGE GLUE SCHEDULE DOWN TIME AT LID  
ATTACHMENT PROCESS FOR SEMICONDUCTOR DEVICES**

**ROZEANA ABD RAHMAN**

**A thesis submitted  
in fulfilment of the requirements for the degree of  
Master of Manufacturing Engineering**

**Faculty of Manufacturing Engineering**

**UNIVERSITI TEKNIKAL MALAYSIA MELAKA**

**2017**

**BORANG PENGESAHAN STATUS LAPORAN PROJEK SARJANA**

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**SESI PENGAJIAN: 2016/2017**

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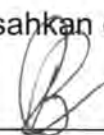
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## **DEDICATION**

To my beloved father, mother and husband.

## ABSTRACT

This research report presents the work done on the improvement of change glue schedule down time at lid attachment process for semiconductor devices. Lid attachment is the end of line process for Plastic Dual Small Outline Flat (PDSOF) package which is one of the semiconductor devices. The process is started with pick and places the lid onto the package, then proceeds to glue dispensing with dosage on four corners of the lids to completely seal the package by using capillary effect. There is a change of glue activity in this process which is counted under schedule down time. Based on the Overall Equipment Effectiveness (OEE), it was found that the change of glue activity give impact on the machine performance. The increasing of change glue time will result in the production did not achieve the target productivity. In this research, the hidden losses were defined on the equipment setup which is changed of glue in the lid attachment process. There is plan to increase the amount of glue lid attach to reduce the schedule down time in order to improve overall equipment effectiveness toward achieving good productivity. The study for glue pot life is required since increasing the amount of glue will extend the glue pot life and it is suspected will increase the glue viscosity. In general, all the project objective are managed to be achieved using the developed research methodology. For future work, this research should be enhance further to achieve better result and to make use of the increasing glue amount and pot life extended time enhancement in other perspective field and also to carry out further study to improve on the whitish on lid surface.



## **ABSTRAK**

Laporan penyelidikan ini membentangkan kerja yang dilakukan pada peningkatan perubahan jadual turun masa penukaran gam pada proses lekatan tudung penutup untuk peranti semikonduktor. Lekatan tudung penutup adalah proses talian terakhir bagi Plastic Dual Kecil Rangka Flat (PDSOF) pakej yang merupakan salah satu daripada peranti semikonduktor. Proses ini bermula dengan pengambilan dan meletakkan tudung ke pakej, kemudian meneruskan untuk pemancutan gam dengan dos yang betul pada empat penjuru tudung untuk melekatkan pakej sepenuhnya dengan menggunakan kesan kapilari. Terdapat aktiviti penukaran gam dalam proses ini yang dikira di bawah jadual turun masa (SDT). Berdasarkan Keberkesanan keseluruhan peralatan (OEE), didapati bahawa aktiviti penukaran gam memberi kesan ke atas prestasi mesin. Peningkatan masa penukaran gam menyebabkan pengeluaran tidak mencapai sasaran produktiviti. Dalam kajian ini kerugian tersembunyi telah ditakrifkan pada persediaan peralatan yang merupakan penukaran gam dalam proses lekatan tudung penutup. Terdapat rancangan untuk menambah jumlah gam untuk mengurangkan jadual turun masa (SDT) untuk memperbaiki keseluruhan keberkesanan peralatan (OEE) ke arah untuk mencapai produktiviti yang baik. Kajian terhadap kehidupan gam periuk diperlukan bagi peningkatan jumlah gam yang akan memanjangkan jangka hayat gam periuk dan disyaki akan meningkatkan kelikatan gam itu. Secara umum, semua objektif projek ini berjaya dicapai dengan menggunakan kaedah penyelidikan yang telah ditetapkan. Untuk kerja-kerja masa depan, penyelidikan ini perlu diperbaiki lagi untuk mencapai keputusan yang lebih baik dan untuk menggunakan jumlah gam dengan periuk peningkatan masa hidup dilanjutkan bagi diaplikasikan dalam bidang perspektif lain dan juga untuk menjalankan kajian lanjut untuk mengatasi masalah keputihan di permukaan tudung.

## ACKNOWLEDGEMENTS

First and foremost, i would like to take this opportunity to express my sincere acknowledgement to my supervisor Professor Dr. Bashir Mohamad Bin Bali Mohamad form Falcuty of Manufacturing Engineering University Technical Malaysia Melaka (UteM) for his essential supervision, support and encouragement and support towards the completion of this master project.

I would also like to express my grestest gratitude to Dr Nur Izan Shahriah bt Hussein from Faculty of Manufacturing Engineering Universiti Teknikal Malaysia Melaka (UteM) for suggestions and advice to me for the master project accomplishment.

Special thanks to all my beloved father, mother and couse mate for their moral support in completing this master. Lastly thanks to you everyone who had been to the crucial parts of realization of this project.

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## LIST OF ABBREVIATIONS

PDSOF	-	Plastic (Green) Dual Small Outline Flat
SDT	-	Schedule Down Time
OEE	-	Overall Equipment Effectiveness
TPM	-	Total Productive Maintenance
MSL	-	Moisture sensitivity level
FTIR	-	Fourier Transform Infrared Spectroscopy
DOE	-	Design of Experiment
UV	-	Ultra-Violation

## CHAPTER 1

### INTRODUCTION

#### 1.1 Background

Lid attachment is the end of line process for Plastic (Green) Dual Small Outline Flat (PDSOF) package which is one of the semiconductor devices. The process is started with pick and places the lid onto the package, then proceeds to glue dispensing with dosage on four corners of the lids to completely seal the package by using capillary effect. Subsequently the package is cured in the oven at 150 °C for one hour. However during production running, the glue needs to be changed in the middle of production lot. The amount of glue is not sufficient for one lot production which is consisted of 13,440 units. Due to this issue, it has indirectly increase the schedule down time (SDT) and affect the overall machine performance. Figure 1.1 shows how the lid attachment process is look like. In Figure 1.2 described the lid attachment process flow in detail. Form the lid attachment process flow, it can be seen that the problematic area is on the glue dispensing. Therefore this project is focusing on that area in order to improve the SDT of lid attachment process.

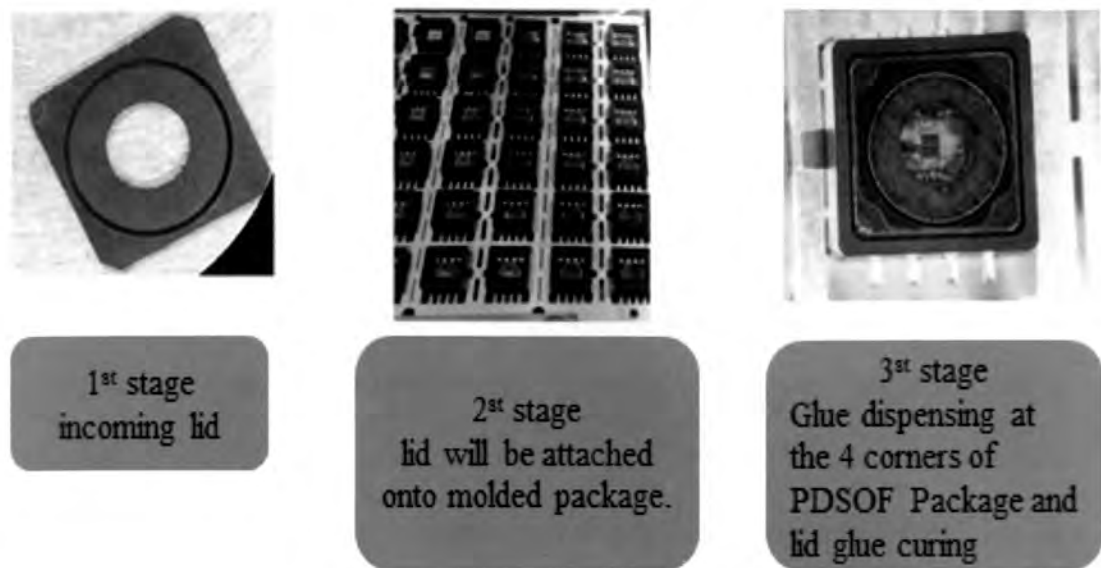


Figure1.1: Lid attachment process

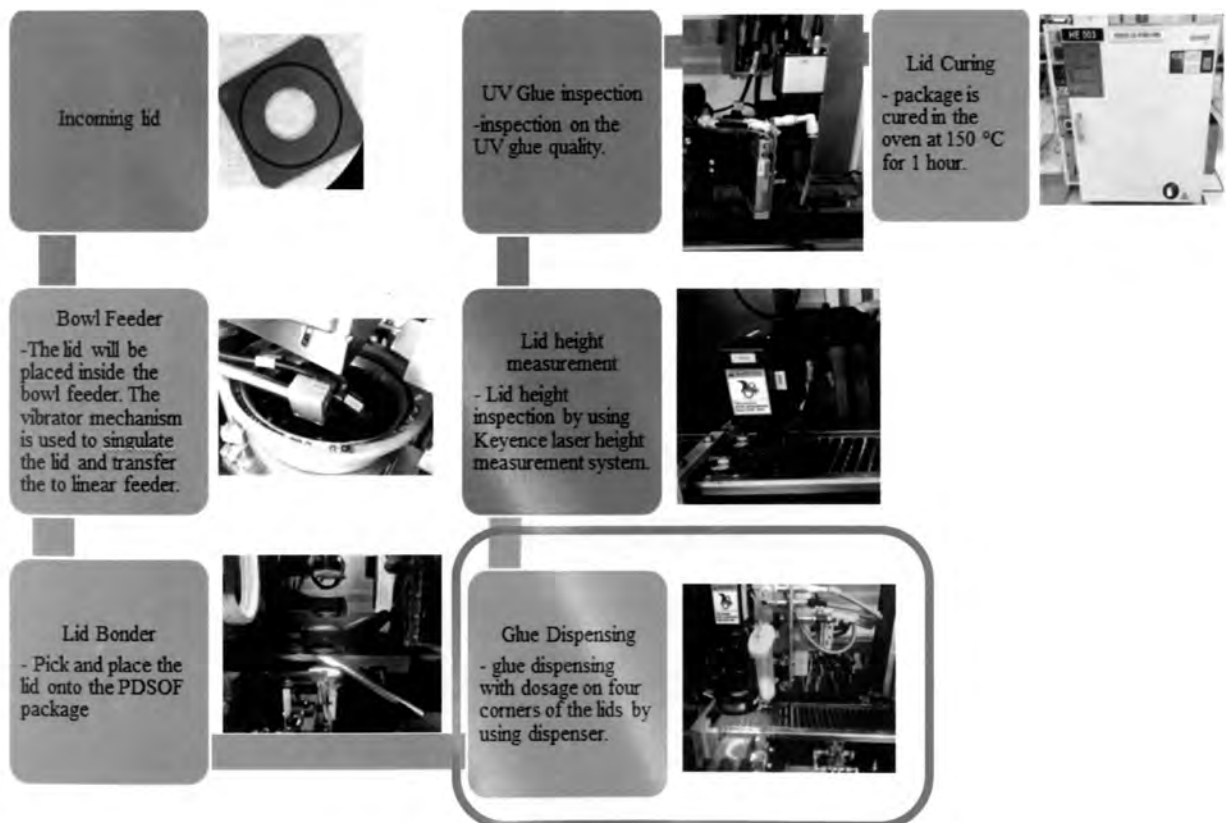


Figure 1.2: lid attachment process flow.



## 1.2 Problem Statement

Infineon Sensor segment is producing semiconductor devices mainly for automotive industry. The demand of semiconductor devices is increasing towards the growth of automotive demand. Due to increasing of PDSOF package form one million per week to 1.6 million per week, production planner found that lid attachment is a bottleneck process and have a potential to cope with the future demand.

Based on weekly machine performance monitoring, it was observed that there is high schedule down time (SDT) for lids attachment process. Table 1.1 shows the figure of Lid attachment weekly machine performance and Table 1.2 shows the breakdown of schedule down time activity at lid attachment process. The current amount of glue lid attachment is not sufficient to support for 13,444 units in one lot production. The machine needs to stop for changing glue activity. In this situation, the machine will stop 15 minutes for this activity. In one day, the machine will be stopped for 10 times for this purpose. This will give huge impact on the productivity losses.

To overcome the high schedule down time (SDT) issues, there is a proposal to increase the amount of glue which is sufficient for one lot of production and can reduce the change glue activities from 10 times per day to 5 times per day. The increasing of the glue amount will extend the glue expired or glue pot life. For current practice, the glue expired limit is 8 hours. However, according to Nagase glue supplier, glue expired limit can be extended for more than 8 hours. In response to this problem, this project is propose to study the glue pot life and to measure how the change glue activity can reduce the schedule down time (SDT) of lid attach process.

Table 1.1: Lid Attachment weekly machine performance

Machine	Standby		Engineering		Schedule down time		Unschedule down time	
	Actual	Target	Actual	Target	Actual	Target	Actual	Target
ALA-001	0.10%	3%	1.98%	2%	7.36%	7%	2.45%	4%
ALA-002	1.20%	3%	0.10%	2%	7.49%	7%	2.76%	4%
ALA-003	0.09%	3%	0.18%	2%	6.45%	7%	3.04%	4%

Table 1.2: Breakdown of Schedule downtime of lid attachment process

Average of Schedule down time		
Activity	Actual	Target
Change lot	0.4%	0.5%
Change glue	3.1%	2.5%
Change needle	1.1%	1.5%
Service Dispenser	2.5%	2.5%
Total	7.1%	7.0%

### 1.3 Objectives

- To investigate the glue pot life effects in lid attachment performance and process parameter due to increasing of glue amount.
- To monitor the change of glue time towards schedule down time (SDT) reductions in lid attachment process.
- To improve the schedules down time (SDT) of lid attachment process by increasing the amounts of glue lid attachment.

## **1.4 Scope**

The lid attach machine consists of four modules which is loader, unloader, bond head, and dispenser and inspection system. The scope of study is at glue dispensing process in which focuses on Lid Attach machine's module. The second phase of the methodology in chapter 3 will be using the screening procedure in which the numbers of design and material will be reduce after considering the objectives of the project. This study proposes three main phases of the project as follow:

- 1) Phase 1 : Investigate the current procedure and material used
- 2) Phase 2: Design assessment and trial run for data collection.
- 3) Phase 3: Implementation of new glue amount for performance assessment.

## **1.5 Significance of Project**

Upon the successful of this project, it is hope that it can help to improve the overall machine performance and efficiency with reducing the change glue SDT by 1.5% reduction. With this improvement the new demand can be achieve successfully.



## **CHAPTER 2**

### **LITERATURE REVIEW**

#### **2.1 Introduction of Overall Equipment Effectiveness (OEE)**

Due to extreme global competition, all companies are struggling to increase and optimize their productivity in order to stay competitive. This condition has led to the need for more strictly defined productivity metrics that are able to take into important factors, such as equipment availability, performance and quality. In availability factor the measurement is on breakdowns, set-ups time and adjustments required in the process. Performance is measure based on reduced speed, idling time and minor stoppages on one equipment or process. While the example of quality such as defects, rework and yield. OEE is the good tool to do the analysis to know how well the equipment or process in order to get the good productivity. Form the OEE also we will know which element needs to be improved in the process.

As mentioned by Campbell,(1995) OEE commonly used measures of maintenance performance into three categories on the basis of their focus; measures of equipment performance (availability, reliability, overall equipment effectiveness), measures of cost performance (operation & maintenance labour and material costs) and measures of process performance (ratio of planned and unplanned work, schedule compliance). The total productive maintenance concept has provided a quantitative metric, Overall Equipment Effectiveness for measuring the productivity of individual production equipment in a factory.

OEE is a tool developed by S. Nakajima (1988) who proposed this in order to evaluate the progress of Total Productive Maintenance (TPM) that he originally created. While Jeong, (2001) mentioned that OEE is the multiplication of three factors; availability, performance and quality. Its particularity is that the hidden losses are taken into consideration in order to higher the degree of significance regarding equipment utilization. However Ljungberg, (1998) mentioned that before the creation of OEE, availability was the only parameter considered which falsified the final result, and an overestimation of equipment utilization was observed. Figure 2.1 is a representation of how OEE could be defined, gathering all the key functions affecting the final result. Moreover, some other losses could be added to get even more accurate results. Based on Aurelian Narses, (2013), planned maintenance for example can be added or focused maintenance time, where the machine could be turned down while improvements are performed on the system.

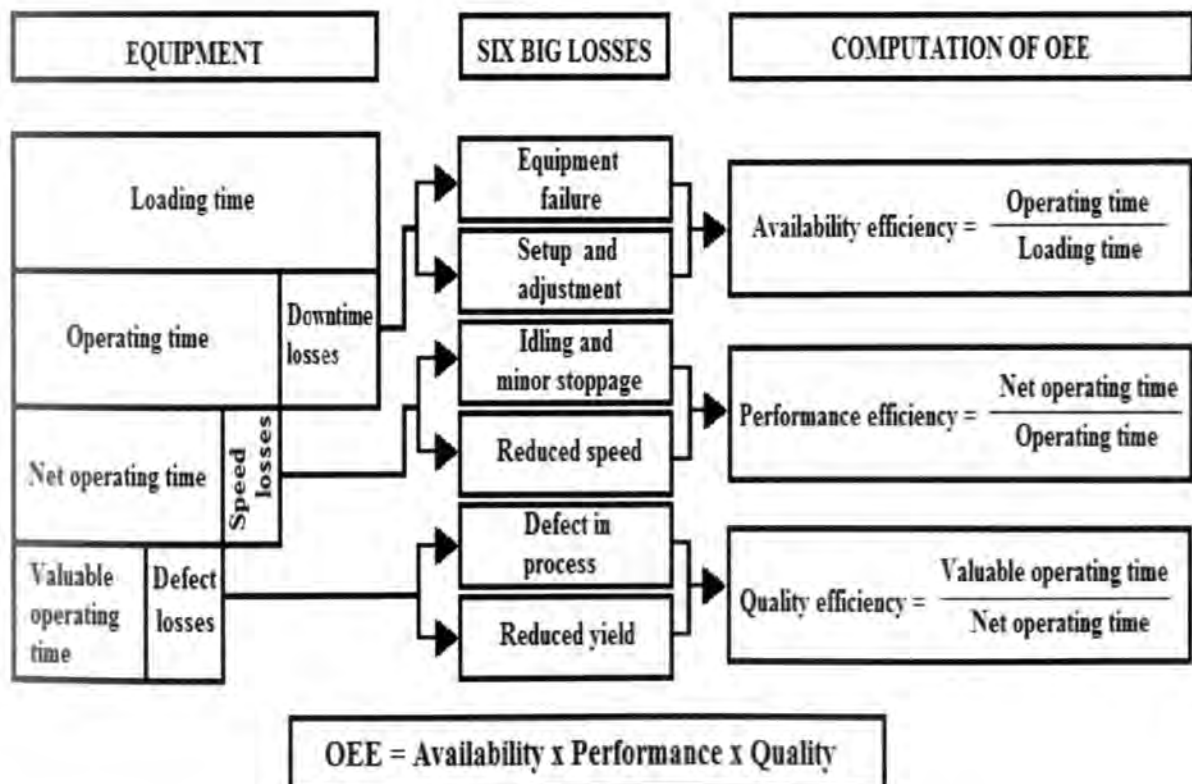


Figure 2.1: OEE computation and procedure (Nakajima, 1988)



OEE can be defined as “A bottom-up approach where an integrated workforce strives to achieve overall equipment effectiveness by eliminating the six big losses” (Nakajima 1988). Six Big Losses describes the most common causes for efficiency loss that almost always found in today's manufacturing environment. Vorne Industries, (2002) also mentioned about six root causes of loss are presented, each directly related to an OEE Factor.

“Six big losses” are defined as follows:

1. Equipment failure/breakdown losses are categorized as time losses when productivity is reduced, and quantity losses caused by defective products.
2. Set-up/adjustment time losses result from downtime and defective products that occur when production of one item ends and the equipment is adjusted to meet the requirements of another item.
3. Idling and minor stop losses occur when the production is interrupted by a temporary malfunction or when a machine is idling.
4. Reduced speed losses refer to the difference between equipment design speed and actual operating speed.
5. Reduced yield occurs during the early stages of production from machine start up to stabilization.
6. Quality defects and rework are losses in quality caused by malfunctioning production equipment. The first two big losses are known as downtime losses and are used to help calculate a true value for the availability of a machine. The third and fourth big losses are speed losses that determine the performance efficiency of a machine such the losses which occur as a consequence operating at less than the optimum conditions. The final two losses are considered to be losses due to defects,